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**INFORMATION DISCLOSURE  
STATEMENT BY APPLICANT**  
(use as many sheets as necessary)

**COMPLETE IF KNOWN**

Application Number 09/018,783  
Confirmation Number 1242  
Filing Date 2/4/98  
First Named Inventor Ritzdorf  
Group Art Unit 2823  
Examiner Name Deven M. Collins

Attorney Docket No. 29195.8162US

Sheet 1 of 3

**U.S. PATENT DOCUMENTS**

EXAMINER INITIALS	Cite No.	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
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**OTHER PRIOR ART-NON PATENT LITERATURE DOCUMENTS**

EXAMINER INITIALS	Cite No.	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume/issue number(s), publisher, city and/or country where published.
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